



Product Change Notification - LIAL-19RTVJ812

Date:

27 Jun 2018

Product Category:

Memory; Real-Time Clock/Calendar

Affected CPNs:**Notification subject:**

CCB 3230 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L MSOP package at MTAI assembly site.

Notification text:**PCN Status:**

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L MSOP package at MTAI assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash(CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	Au	CuPdAu
Die attach material	8390A	8390A
Molding compound material	G600V	G600V
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 27, 2018 (date code: 1830)



NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	April 2018					-->	June 2018					July 2018				
	14	15	16	17	18		22	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date				X												
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date														X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

April 23, 2018: Issued initial notification.

June 27, 2018: Issued final notification. Attached the Qualification Report and provided estimated first ship date to be on July 27, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_LIAL-19RTVJ812_QUAL_PLAN.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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